

# SOT894-1

plastic low profile fine-pitch ball grid array package; 280 balls; body 11 x 11 x 1 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFBGA280
<b>Package type industry code</b>	LFBGA280
<b>Package style descriptive code</b>	LFBGA (low profile fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	16-3-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	10.9	-	11	11.1	mm
E	package width	10.9	-	11	11.1	mm
A	seated height	[tbd]	-	1.4	1.4	mm
A <sub>2</sub>	package height	0.9	-	1	1.1	mm
n <sub>2</sub>	actual quantity of termination	-	-	280	-	



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## 2. Package outline

LFBGA280: plastic low profile fine-pitch ball grid array package; 280 balls; body 11 x 11 x 1 mm SOT894-1

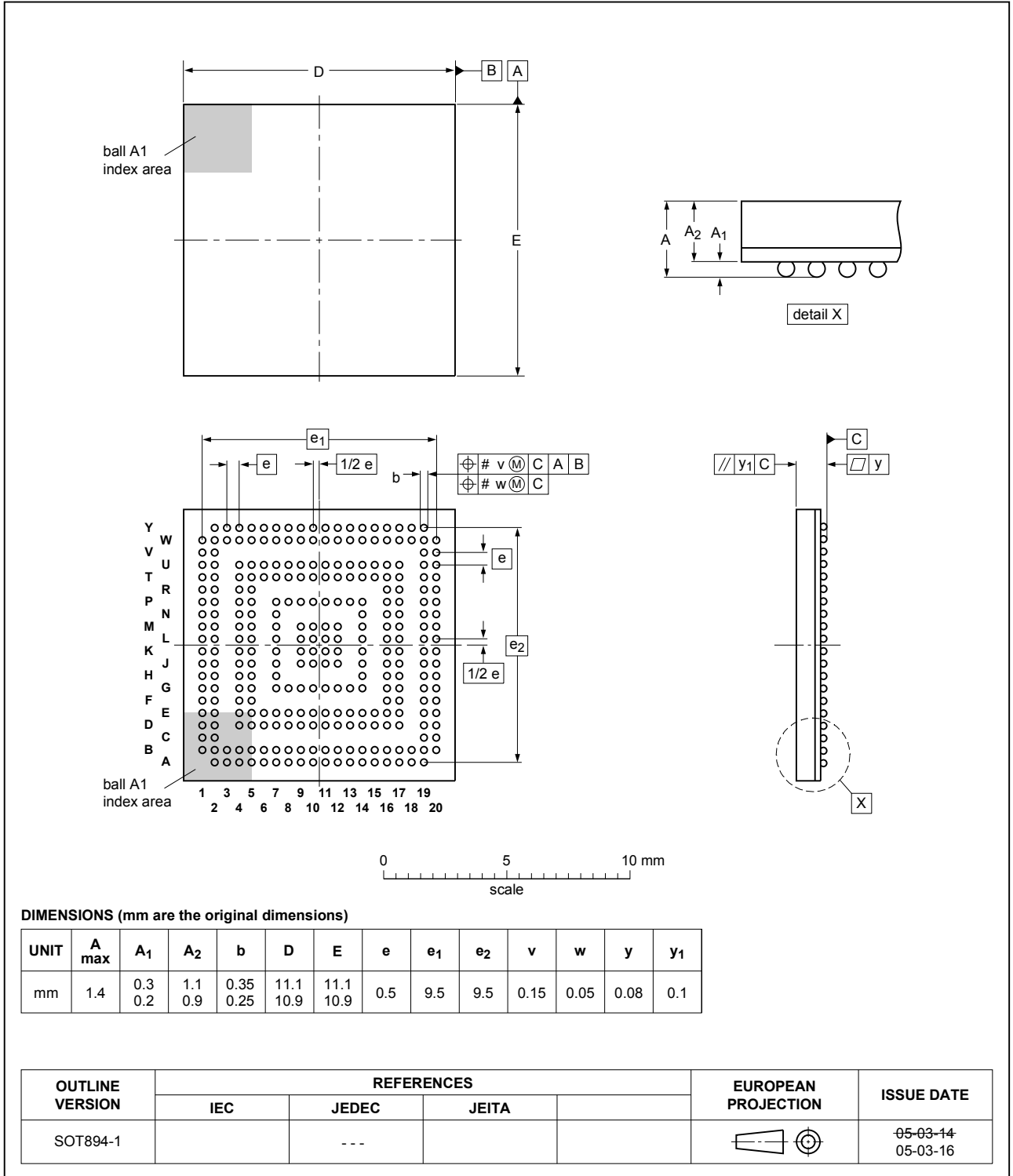
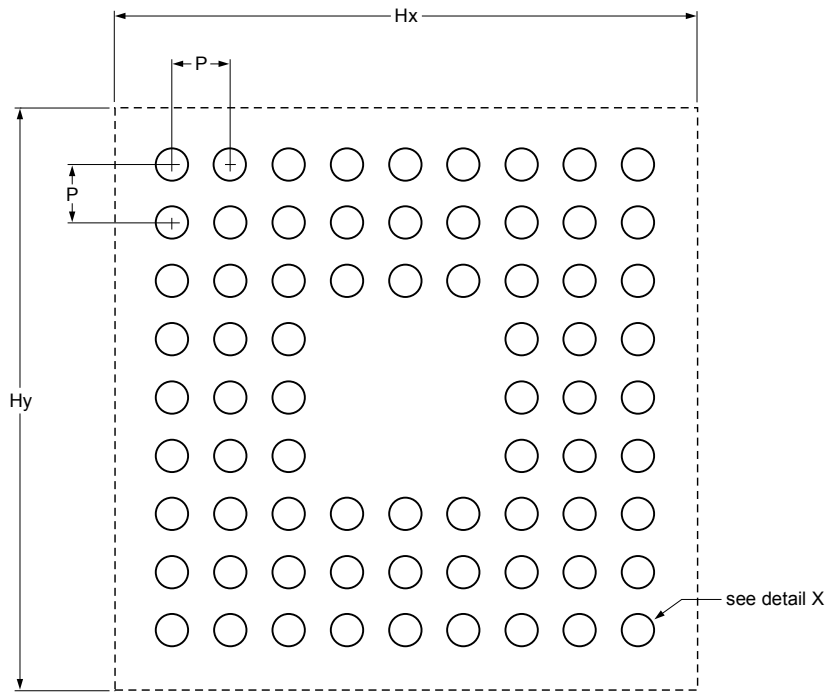


Fig. 1. Package outline LFBGA280 (SOT894-1)

### 3. Soldering

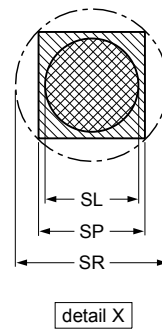
Footprint information for reflow soldering of LFBGA280 package

SOT894-1



Generic footprint pattern  
Refer to the package outline drawing for actual layout

- solder land
- solder paste deposit
- solder land plus solder paste
- occupied area
- solder resist



DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.50	0.275	0.300	0.425	11.400	11.400

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Fig. 2. Reflow soldering footprint for LFBGA280 (SOT894-1)

## 4. Legal information

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## 5. Contents

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1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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Date of release: 8 February 2016

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